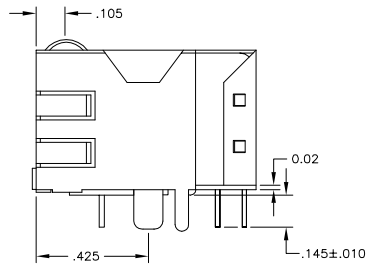
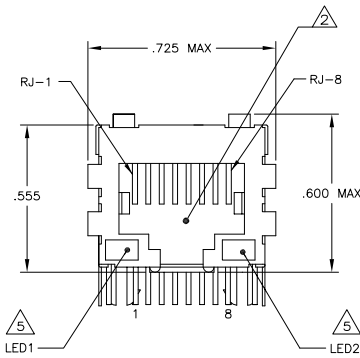
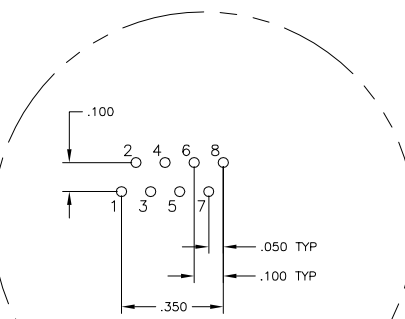
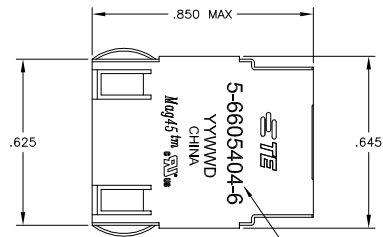


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LOC	REV	DESCRIPTION	DATE	BY	APP
AA	22				
B	ECO-08-022357		01DEC2008	QL	TX
C	ECO-11-015766		30MAY2011	EL	LR

MECHANICAL:



MATERIALS:
 HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0
 SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30µINCH SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100µINCH MIN SAC SOLDER.
 MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50µINCH MIN OVERALL NICKEL UNDERPLATE, WITH SELECT 50µINCH MIN HARD GOLD FINISH PLATE SOLDER TAILS WITH 100µINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
 LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" x .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80µINCH SILVER OVER 40µINCH NICKEL UNDERPLATE OVER 40µINCH COPPER UNDERPLATE. POST-PLATED WITH 100µINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.

RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.

MAGNETICS
 -IMPEDANCE: 100 OHMS
 -TURNS RATIO (CHIP: CABLE): TX = 1:1, RX = 1:1
 -OPEN CIRCUIT INDUCTANCE (OCL): 350µH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM -40°C TO +85°C, TX AND RX
 -PERFORMANCE @ 25°C:
 INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 12dB MIN FROM 60.1MHz TO 80MHz
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 4.0MHz
 33-20*LOG(f/50)dB MIN FROM 4.01MHz TO 100MHz
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 -ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC.

4. OPERATING TEMPERATURE: FROM -40°C TO +85°C INDUSTRIAL TEMPERATURE RATED.

LEDs ARE DRIVEN WITH CONSTANT CURRENT AT APPROX 20 mA
 LED COLOR: DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP @ IF=20 mA
 FORWARD VOLTAGE (VF): GREEN 2.2V TYP @ IF=20 mA
 DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP @ IF=20 mA
 FORWARD VOLTAGE (VF): YELLOW 2.1V TYP @ IF=20 mA

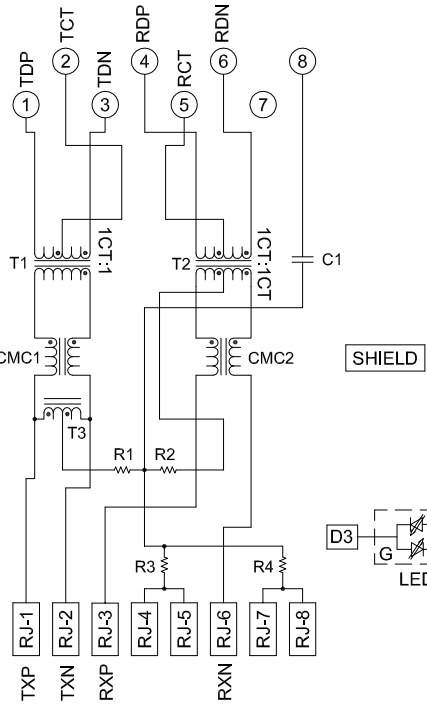
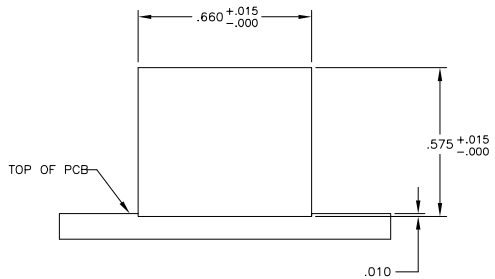
INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE ASYMMETRIC, AND THEREFORE DO NOT SUPPORT AUTO-MDI/MDIX.

TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.

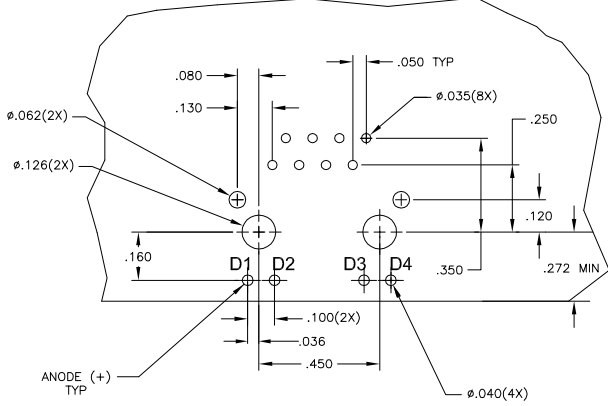
8. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

ELECTRICAL:

414ETP1 SERIES MAGNETIC CIRCUIT



C1 = 1000 pF, 2kV DECOUPLING CAPACITOR
 R1-R4 = 75 OHMS, 1/16 W, 5% RESISTORS



Suggested PCB Layout
 (Component Side)

GREEN/YELLOW	GREEN/YELLOW	5-6605404-6
LED1	LED2	PART NUMBER

DIMENSIONS:		REV. ATTADIA - 07MAR2008		REV. FAROLE - 07MAR2008	
INCHES	NO. PARTS	NO. PARTS	NO. PARTS	NO. PARTS	NO. PARTS
0 P.C.	± .010	1 P.C.	± .010	2 P.C.	± .010
3 P.C.	± .005	4 P.C.	± .005	ANGLES	± .005
MATERIAL		FINISH		WEIGHT	
A1		A1		A1	
CUSTOMER DRAWING		SCALE		SHEET 1 OF 1	